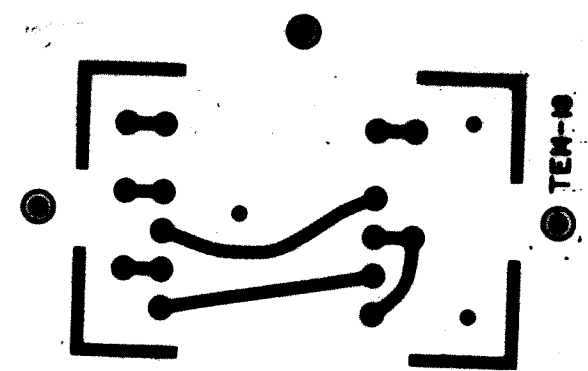


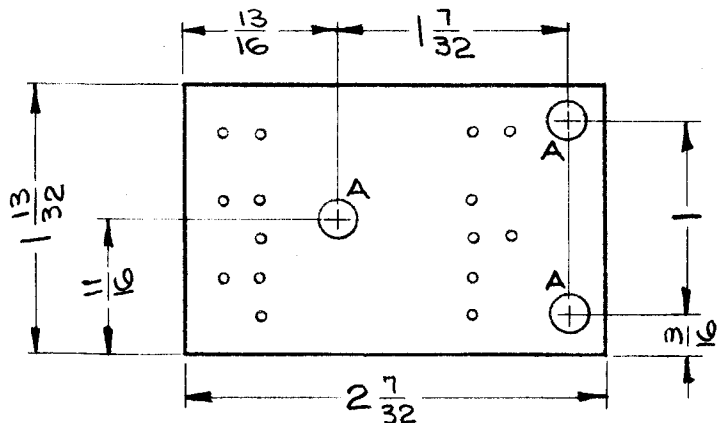
SCALE - 1:1
PRINTED CIRCUIT (COMPONENT SIDE) A 3269
CAUTION - THIS SIDE UP WHEN PRINTING



PRINTED CIRCUIT A 3269 SCALE 1:1
CAUTION THIS SIDE UP WHEN PRINTING

ORIGINAL ARTWORK TO BE REMOVED FROM PROTECTIVE POCKETS WHEN PHOTOGRAPHING.

ETCHING, PRINTED CIRCUIT (A 3269-1)



MACHINING (A 3269-2)
DO NOT SCALE WORK TO DIMENSIONS

1	VLR-1	AX 434
Q'TY./UNIT	MODEL USED ON	ASS'Y. NO.
SCALE 1:1	CODE A	

THE CONTENTS OF THIS DRAWING ARE THE EXCLUSIVE PROPERTY OF THE TECHNICAL MATERIEL CORP. ITS UNAUTHORIZED USE OR REPRODUCTION IN WHOLE OR IN PART IS STRICTLY FORBIDDEN.

A 3269

REVISIONS					
SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD APPD
X1	COMPLETELY REDRAWN	9-16-63	1	G.S.	
Q	ORIGINAL RELEASE FOR PRODUCTION	5-12-64	0	A.M.	

HOLE & PAD SPECIFICATIONS			
HOLE	DIA.	PAD DIA.	REQ
UNMARKED	.050	.130	15
A	.189		3

NOTES: TO BE MANUFACTURED IN ACCORDANCE WITH TMC SPEC. S-735, UNLESS OTHERWISE SPECIFIED.

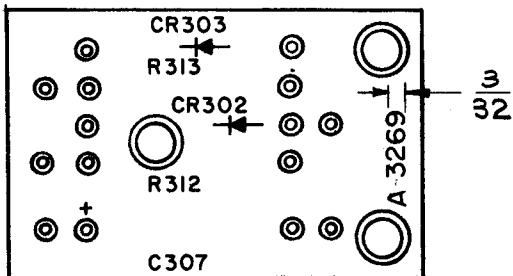
- MATERIAL - G-10 EPOXY GLASS LAMINATE 3/32 THICK, 2 OUNCE COPPER CLAD BOTH SIDES.
- ALL BOARDS WILL BE DOUBLE-SIDED. WHENEVER A PAD APPEARS ON THE PRINTED CIRCUIT SIDE, A SIMILAR SIZE AND SHAPE SHALL APPEAR ON THE COMPONENT SIDE IN EXACT REGISTER. (EXCEPT WHERE AN EXCEPTION IS NOTED.)
- (A) ALL HOLES EXCEPT "A" MTG. HOLES ARE TO BE PLATED-THRU WITH A MINIMUM COPPER PLATING THICKNESS OF .001.

(B) PLATE .0003 TO .0005 NICKEL & 25 MILLIONTHS MINIMUM OF GOLD ALL ETCHED SURFACES & PLATED-THRU HOLES.
- CONDUCTOR WIDTH: .046 MIN., .062 MAX.
SPACE BETWEEN CONDUCTORS .031 MIN.

THE ORIGINAL ARTWORK TO BE SUPPLIED BY TMC FOR PHOTOGRAPHING (SCALE 1:1)

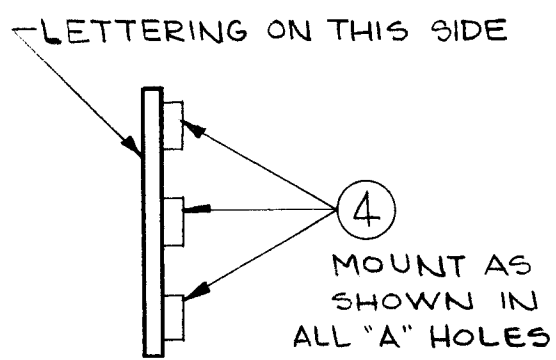
REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
M. GELLMAN		LIST OF MATERIAL		
MATERIAL		THE TECHNICAL MATERIEL CORP. MAMARONECK, NEW YORK		
FINISH		TITLE PRINTED CIRCUIT BOARD, ASSY. (MAIN CHASSIS)		
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES		DRAWN <i>G. Jones</i>	DATE 9-16-63	FINAL APPROVAL <i>RJC</i>
		CHECKED <i>@</i>	DATE 5-5-64	
DECIMALS .X ± .05 .XX ± .01 .XXX ± .005		ELECT. DES. <i>MJS</i>	DATE 5-7-64	A 3269
FRACTIONS ± 1/64 ANGLES ± 0° 30'		MECH. DES. <i>MJS</i>	DATE 5-7-64	REV. LTR.
TOLERANCES		SHEET 1 OF 2		

NOTES

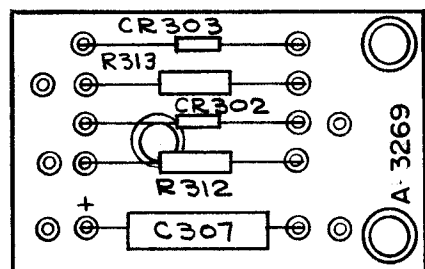


- UNLESS OTHERWISE SPECIFIED -
- 1- ALL LETTERING TO BE 5/64 HIGH BLACK GOTHIC.
 - 2- LETTERING TO BE PLACED ± 1/64.
 - 3- MARKING PROCESS: AS PER TMC SPEC S-727.

MARKING (A 3269-3)

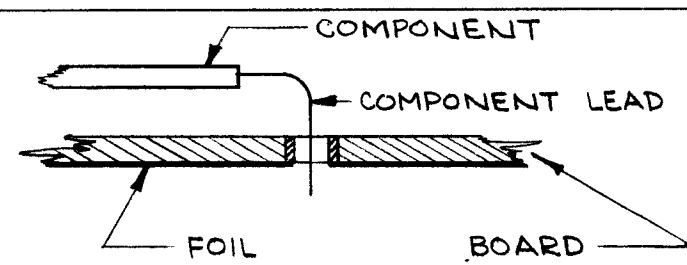


SUB-ASSY (A 3269-4)



ELECTRICAL ASSY (A 3269-5)

- ASSEMBLY NOTICE -
- 1- TO MOUNT COMPONENTS INSERT LEAD THROUGH PLATED-THRU HOLES & BEND ABOUT 1/16 OF LEAD OVER COPPER FOIL AS SHOWN.
 - 2- APPLY HEAT & SOLDER TO LEAD & FOIL - CAUTION - TOO MUCH HEAT WILL CAUSE THE FOIL TO SEPARATE FROM THE BOARD.
 - 3- CLEAN & INSPECT AS PER S-676.
 - 4- FUNGUS PROOFING PER TMC SPECIFICATION S113.



1	VLR-1	AX-434
Q'TY./UNIT	MODEL USED ON	ASS'Y. NO.
SCALE 1:1	CODE A	

NOTES

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A 3269

REVISIONS

SYM	DESCRIPTION	DATE	E.M.N. NO.	DRAFT	CHKD	APPD
X1	COMPLETELY REDRAWN	9-16-63	1	G.S.		
Ø	ORIGINAL RELEASE FOR PRODUCTION	5/12/64	0	A.M.	@	

REQ'D.	ITEM	PART NUMBER	DESCRIPTION	SYMBOL
X	5	BS 100	SOLDER, SOFT	
3	4	TE 164-7	STANDOFF, RIVET TYPE	
1	3	CE 105-50-15	MINIATURE ELECTROLYTIC CAP	C307
2	2	RC 20 GF 222 J	RESISTOR, FIXED, COMPOSITION	R312, 313
2	1	IN 34 A	DIODE	CR302, 303

M. GELLMAN LIST OF MATERIAL

THE TECHNICAL MATERIEL CORP.
MAMARONECK, NEW YORK

TITLE PRINTED CIRCUIT BOARD, ASSY.
(MAIN CHASSIS)

DRAWN G. Jensen	DATE 9-16-63	FINAL APPROVAL RJC	DATE
CHECKED @	DATE 5-5-64		
ELECT MJA	DATE	A 3269	Ø
MECH DES WJS	DATE 5-7-64	SHEET 2 OF 2	REV. LTR.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES AND INCLUDE CHEMICALLY APPLIED OR PLATED FINISHES

DECIMALS .X ± .05 .XX ± .01 .XXX ± .005	TOLERANCES	FRACTIONS ± 1/64 ANGLES ± 0° 30'
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